

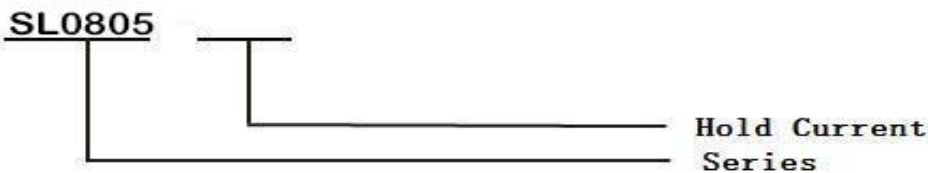
## Feature

- Resettable over current and over temperature protection
- Small size of 0805
- Small footprint
- Low resistance
- Fast time-to-trip
- ROHS complaint

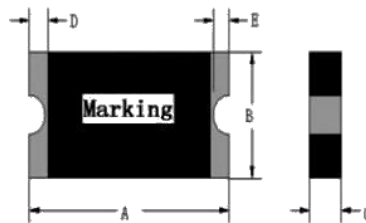
## Application

- Computer
- Battery
- Mobile phones
- Industrial controls
- Automotive
- Portable electronics
- Multimedia
- Game machines
- Telephony and broadband

## Part Numbering



## Product Dimensions in Millimeter



Part Number	A		B		C		D	E
	Min	Max	Min	Max	Min	Max	Min	Min
SL0805075	1.90	2.50	1.20	1.80	0.4	1.0	0.20	0.10
SL0805110	1.90	2.50	1.20	1.80	0.5	1.2	0.20	0.10
SL0805125	1.90	2.50	1.20	1.80	0.5	1.2	0.20	0.10
SL0805150	1.90	2.50	1.20	1.80	0.5	1.2	0.20	0.10
SL0805175	1.90	2.50	1.20	1.80	0.6	1.3	0.20	0.10
SL0805200	1.90	2.50	1.20	1.80	0.6	1.3	0.20	0.10
SL0805260	1.90	2.50	1.20	1.80	0.6	1.5	0.20	0.10
SL0805300	1.90	2.50	1.20	1.80	0.6	1.5	0.20	0.10
SL0805350	1.90	2.50	1.20	1.80	0.6	1.5	0.20	0.10
SL0805380	1.90	2.50	1.20	1.80	0.6	1.5	0.20	0.10

**Electrical Characteristics**

Part Number	I(A)		V <sub>max</sub>	I <sub>max</sub>	Pd <sub>typ</sub>	T <sub>trip</sub>		R <sub>min</sub>	R <sub>max</sub>	R <sub>1max</sub>
	25°C					25°C				
	Hold	Trip	(V)	(A)	(W)	Current(A)	Time(S)	(Ω)	(Ω)	(Ω)
SL0805075	0.75	1.5	6.0	50	1.0	8.0	0.3	0.025	0.048	0.080
SL0805110	1.10	2.2	6.0	50	1.0	8.0	0.5	0.020	0.044	0.075
SL0805125	1.25	2.5	6.0	50	1.0	8.0	1.0	0.015	0.040	0.070
SL0805150	1.50	3.0	6.0	50	1.0	8.0	5.0	0.010	0.036	0.065
SL0805175	1.75	3.5	6.0	50	1.0	8.0	5.0	0.008	0.032	0.060
SL0805200	2.00	4.0	6.0	50	1.0	8.0	5.0	0.008	0.028	0.055
SL0805260	2.60	5.2	6.0	50	1.0	12.0	5.0	0.007	0.024	0.050
SL0805300	3.00	6.0	6.0	50	1.0	12.0	5.0	0.007	0.020	0.045
SL0805350	3.50	7.0	6.0	50	1.0	12.0	5.0	0.006	0.018	0.040
SL0805380	3.80	7.6	6.0	50	1.0	12.0	5.0	0.006	0.015	0.035

I<sub>H</sub>=Hold current: maximum current at which the device will not trip at 25°C or 60°C still air reflow soldering of 260°C for 20 sec.

I<sub>T</sub>=Trip current: minimum current at which the device will always trip at 25°C still air reflow soldering of 260°C for 20 sec.

V<sub>max</sub>=Maximum continuous voltage device can withstand without damage at rated current

I<sub>max</sub>=Maximum fault current device can withstand without damage at rated voltage.

T<sub>trip</sub>=Maximum time to trip(s) at assigned current reflow soldering of 260°C for 20 sec.

Pd<sub>typ</sub>=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R<sub>min</sub>= Minimum resistance of device in initial (un-soldered) state.

R<sub>max</sub>= Maximum resistance of device in initial (un-soldered) state.

R<sub>1max</sub>=Maximum resistance of device at 25°C measured one hour after reflow soldering of 260°C for 20 sec.

**Value specified is determined by using the PWB with 0.030" \*1.5oz coppertraces.**

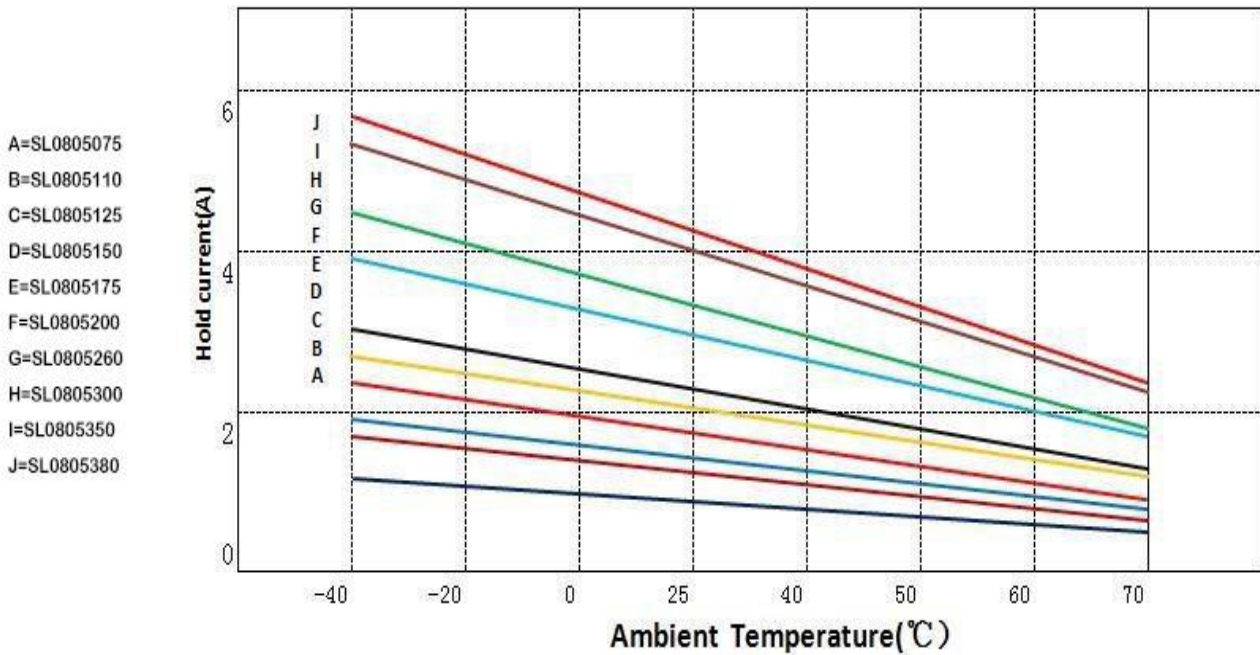
**Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.**

**Environmental Specifications**

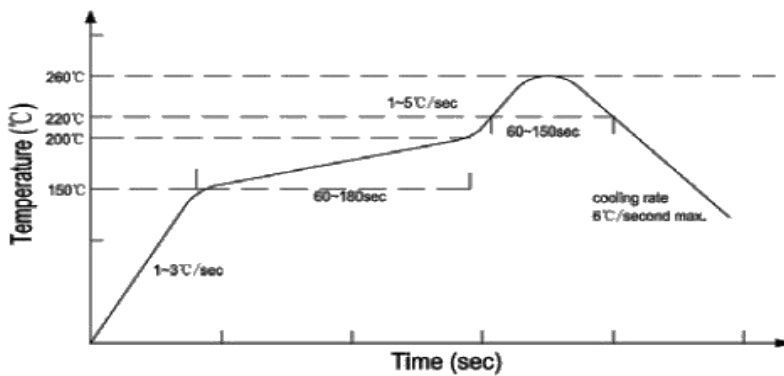
Test	Test Conditions	Resistance Change/ Criteria
Recommended storage conditions	40°C max, 70% R.H. max	± 5%
Passive aging:	85°C, 1000 hours	≤ R <sub>1max</sub>
Moisture Resistance	85% RH, 85°C, 1000hrs	≤ R <sub>1max</sub>
Thermal Shock	MIL-STD-202 Method 107G +85°C /-40°C 20 times	≤ R <sub>1max</sub>
Vibration	MIL-STD-883C, Method 2007.1, Condition A	± 5%
Solvent Resistance	MIL-STD-202, Method 215	Appearance No change
Moisture Level Sensitivity	J-STD-020C	Level 2a

Thermal Derating [ Hold Current (A) at Ambient Temperature (°C)]

Part Number	Maximum Ambient Operating Temperature (°C)							
	-40	-20	0	25	40	50	60	70
SL0805075	1.1	1.0	0.8	0.75	0.7	0.6	0.5	0.4
SL0805110	1.7	1.4	1.2	1.10	1.0	0.8	0.7	0.6
SL0805125	1.9	1.6	1.4	1.25	1.1	0.9	0.8	0.7
SL0805150	2.3	2.0	1.7	1.50	1.4	1.1	1.0	0.9
SL0805175	2.6	2.3	1.9	1.75	1.6	1.2	1.1	1.0
SL0805200	3.0	2.6	2.2	2.00	1.8	1.4	1.3	1.2
SL0805260	3.9	3.4	2.9	2.60	2.3	1.8	1.7	1.6
SL0805300	4.5	3.9	3.3	3.00	2.7	2.1	2.0	1.8
SL0805350	5.3	4.6	3.9	3.50	3.2	2.5	2.3	2.1
SL0805380	5.7	4.9	4.2	3.80	3.4	2.7	2.5	2.3



Solder Reflow Recommendation



Reflow -curve

Recommended reflow methods: IR, hot air oven, nitrogen oven

**Surface-Mount Device**

**SL0805**

ROHS 

Devices can be cleaned using standard industry methods and solvents.

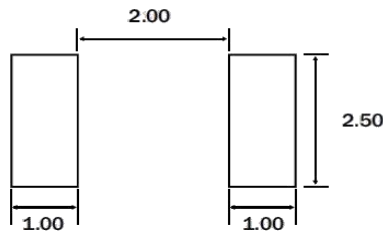
**NOTE:**

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

**Caution:** Operation beyond the rated voltage or current may result in rupture electrical arcing or flame

**Packaging Quantity and Marking**

Recommended Pad Layout (mm.)



Device	Standard Quantity (pcs)
SL0805075	4000
SL0805110	4000
SL0805125	4000
SL0805150	4000
SL0805175	4000
SL0805200	4000
SL0805260	4000
SL0805300	4000
SL0805350	4000
SL0805380	4000

 **CAUTION:**

Operation beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame. The devices are intended for protection against occasional over-current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated. Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.

**Contact information**

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Rev. letter		Date	
Design	Check	Audit	Approve

单击下面可查看定价，库存，交付和生命周期等信息

[>>SEA-LAND\(台湾陆海\)](#)